

**AMENDMENTS TO THE SPECIFICATION**

**IN THE TITLE**

**Please amend the title as it appears on the first page of the specification and in the U.S. Patent and Trademark Office's records, as follows:**

**METHOD FOR FABRICATING A CHIP PACKAGE SUBSTRATE HAVING  
SOFT CIRCUIT BOARD AND METHOD FOR FABRICATING THE SAME,  
INCLUDING A PLURALITY OF CHIP PACKAGE SUBSTRATES**

**IN THE SPECIFICATION**

**Please add the following paragraph after the paragraph ending on page 4, line 19:**

Further scope of the applicability of the present invention will become apparent from the detailed description given hereinafter. However, it should be understood that the detailed description and specific examples, while indicating preferred embodiments of the invention, are given by way of illustration only, since various changes and modifications within the spirit and scope of the invention will become apparent to those skilled in the art from this detailed description.

**Please amend the paragraph beginning on page 4, line 21, as follows:**

**The various objects and advantages of the present invention will be become more readily fully understood from the following detailed description when read in conjunction with and the appended accompanying drawings, which are given by way of illustration only, and thus are not limitative of the present invention, and in which:**